Vincotech

30-E312NAA003MS13-PS48F75Z
datasheet

flowANPC E3BP **1200 V / 3 mΩ**

Topology features

- Kelvin Emitter for improved switching performance
- Temperature sensor
- Advanced Neutral Point Clamped topology
- Gate Resistor

Component features

- High Blocking Voltage with low drain source on state resistance
- High speed SiC-MOSFET technology
- Resistant to Latch-up

Housing features

- Base isolation: Al_2O_3
- Cu baseplate
- Convex shaped baseplate for superior thermal contact
- CTI600 housing material
- Baseplate with rough surface
- Thermo-mechanical push-and-pull force relief
- Solder pin

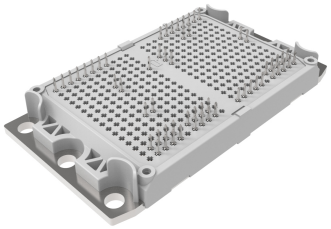
Target applications

- Energy Storage Systems

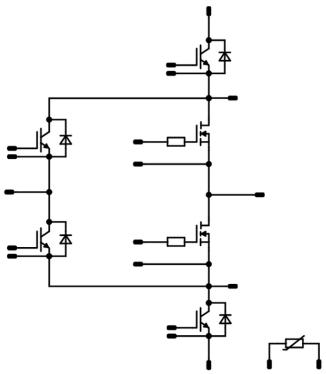
Types

- 30-E312NAA003MS13-PS48F75Z

flow E3BP 12 mm housing



Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
AC Switch				
Drain-source voltage	V_{DSS}		1200	V
Drain current (DC current)	I_D	T_j = T_{jmax} T_s = 80 °C	321	A
Peak drain current	I_{DM}	t_p limited by T_{jmax}	1704	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	400	W
Gate-source voltage	V_{GSS}	static	-5 / 18	V
		dynamic	-10 / 22	V
Maximum Junction Temperature	T_{jmax}		175	°C
Neutral Point Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	T_j = T_{jmax} T_s = 80 °C	256	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	600	A
Turn off safe operating area		T_j = 150°C, V_{CE} = 1200 V	600	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	452	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V T_j = 175 °C	7	µs
Maximum junction temperature	T_{jmax}		175	°C
DC-Link Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	T_j = T_{jmax} T_s = 80 °C	235	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	800	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	376	W
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
DC-Link Switch				
Collector-emitter voltage	V_{CES}		950	V
Collector current (DC current)	I_C	T_j = T_{jmax} T_s = 80 °C	323	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	800	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	375	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Neutral Point Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	T_j = T_{jmax} T_s = 80 °C	189	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	600	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	286	W
Maximum junction temperature	T_{jmax}		175	°C
Resistor (Gate)				
DC current	I	terminal temperature Tk = 90 C°	2121	mA
Power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	1,5	W
Operation Temperature	T_{op}		-55 ... 155	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…+(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6800	V
Creepage distance			>12,7	mm
Clearance			>12,7	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
AC Switch										
Static										
Drain-source on-state resistance	$r_{DS(on)}$		18		426	25 125 150		2,83 3,48 3,83	4,17[1]	mΩ
Gate-source threshold voltage	$V_{GS(th)}$				0,0426	25	1,7	2,25	2,75	V
Gate to Source Leakage Current	I_{GSS}		22	0		25			600	nA
Zero Gate Voltage Drain Current	I_{DSS}		0	1200		25			60	µA
Internal gate resistance	r_g							0,167		Ω
Gate charge	Q_g		-5/18	800	426	25		1128		nC
Short-circuit input capacitance	C_{iss}	f = 500 kHz	0	800	0	25		28080		pF
Short-circuit output capacitance	C_{oss}							1410		
Reverse transfer capacitance	C_{rss}							48		
Diode forward voltage	V_{SD}		0		426	25		4,1		V
Thermal										
Thermal resistance junction to sink[2]	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,24		K/W

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 2 Ω R_{goff} = 2 Ω	-5/18	600	400	25 125 150		59,94 52,47 51,36		ns
Rise time	t_r					25 125 150		37,88 30,82 29,53		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		113,21 128,62 132,73		ns
Fall time	t_f					25 125 150		20,72 18,66 18,8		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=2,52 µC Q_{rFWD}=6,1 µC Q_{rFWD}=7,07 µC				25 125 150		5,99 4,93 4,6		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		6,4 7,31 7,36		mWs
Peak recovery current	I_{RRM}	di/dt=13993 A/µs di/dt=14740 A/µs di/dt=14128 A/µs				25 125 150		150,6 272,81 299,6		A
Reverse recovery time	t_{rr}					25 125 150		27,31 36,23 37,56		ns
Recovered charge	Q_r					25 125 150		2,52 6,1 7,07		µC
Reverse recovered energy	E_{rec}					25 125 150		0,96 2,69 3,19		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		17986,91 33857,42 38345,27		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Neutral Point Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,0068	25	5,15	5,8	6,45	V
Collector-emitter saturation voltage	V_{CEsat}		15		300	25 125 150	1,3	1,58 1,81 1,86	1,7(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			31,2	µA
Gate-emitter leakage current	I_{GES}		20	0		25			400	nA
Internal gate resistance	r_g							0,5		Ω
Input capacitance	C_{ies}	f = 100 kHz	0	25		25		60400		pF
Reverse transfer capacitance	C_{res}							216		pF
Gate charge	Q_g	V_{CC} = 600 V	±15		300	25		5000		nC
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,21		K/W
DC-Link Diode										
Static										
Forward voltage	V_F				400	25 125 150	1,45	2,04 2,06 2,06	1,95(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			4	µA
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,25		K/W

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
DC-Link Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,0065	25	4,15	4,85	5,65	V
Collector-emitter saturation voltage	V_{CEsat}		15		400	25 125 150		1,21 1,23 1,24	1,4[1]	V
Collector-emitter cut-off current	I_{CES}		0	950		25			8	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							0,75		Ω
Input capacitance	C_{ies}	f = 100 kHz	0	25		25		49200		pF
Output capacitance	C_{oes}							530		pF
Reverse transfer capacitance	C_{res}							220		pF
Gate charge	Q_g		±15		0	25		4100		nC
Thermal										
Thermal resistance junction to sink[2]	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,25		K/W
Neutral Point Diode										
Static										
Forward voltage	V_F				300	25 125 150		1,88 1,89 1,87	2[1]	V
Reverse leakage current	I_R	V_r = 1200 V				25			15	µA
Thermal										
Thermal resistance junction to sink[2]	$R_{th(j-s)}$	λ_{paste} = 5,2 W/mK (PTM)						0,33		K/W

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Resistor (Gate)										
Static										
Resistance	R							0,333		Ω
Tolerance							-1		1	%
Temperature coeficient	tc							100		ppm/K
Thermistor										
Static										
Rated resistance	R					25		5		kΩ
Deviation of R100	$\Delta_{R/R}$	R_{100} = 499 Ω				100	3,2		3,3	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3380		K
Vincotech Thermistor Reference									V	

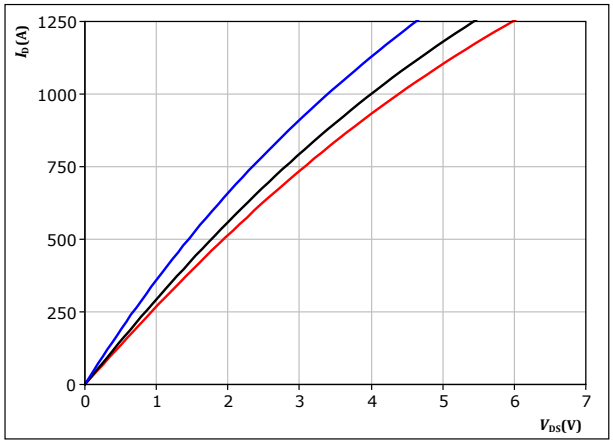
(1) Value at chip level
(2) Only valid with pre-applied Vincotech thermal interface material.

AC Switch Characteristics

figure 1. **MOSFET**

Typical output characteristics

$I_D = f(V_{DS})$



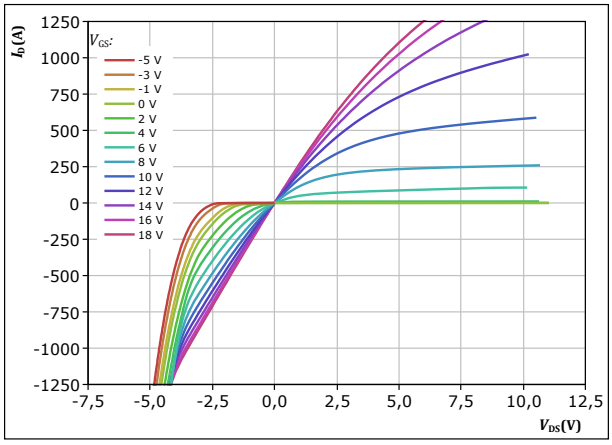
t_p = 250 µs
V_{GS} = 18 V

T_j: 25 °C, 125 °C, 150 °C

figure 2. **MOSFET**

Typical output characteristics

$I_D = f(V_{DS})$

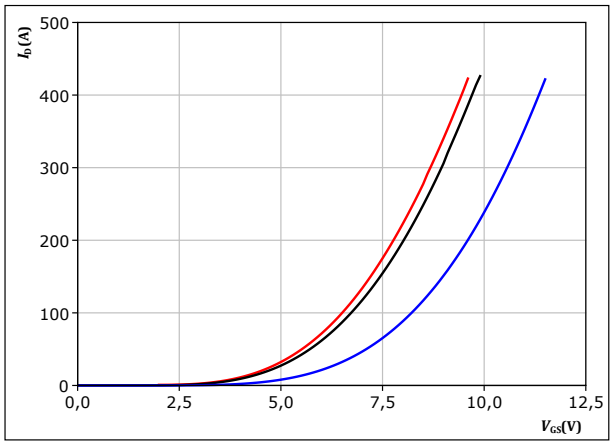


t_p = 250 µs
T_j = 150 °C
V_{GS} from -5 V to 18 V in steps of 2 V

figure 3. **MOSFET**

Typical transfer characteristics

$I_D = f(V_{GS})$



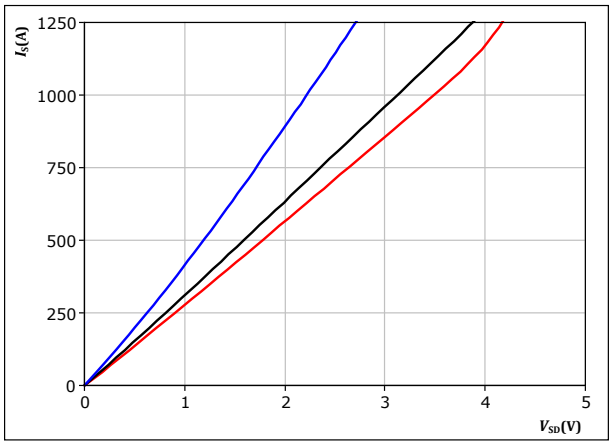
t_p = 250 µs
V_{DS} = 8 V

T_j: 25 °C, 125 °C, 150 °C

figure 4. **MOSFET**

Typical reverse drain current characteristics

$I_{SD} = f(V_{SD})$



t_p = 250 µs
V_{GS} = 18 V

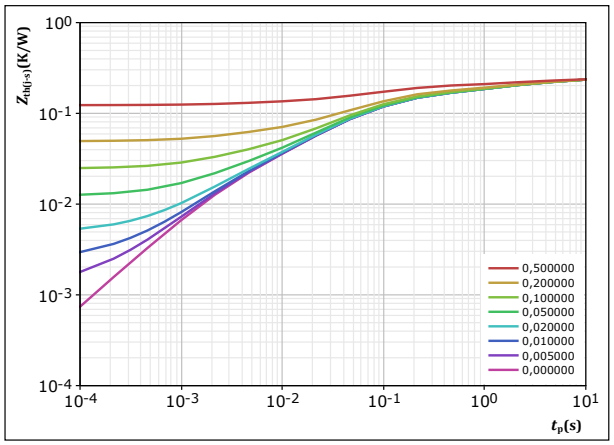
T_j: 25 °C, 125 °C, 150 °C

AC Switch Characteristics

figure 5. **MOSFET**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,237	K/W

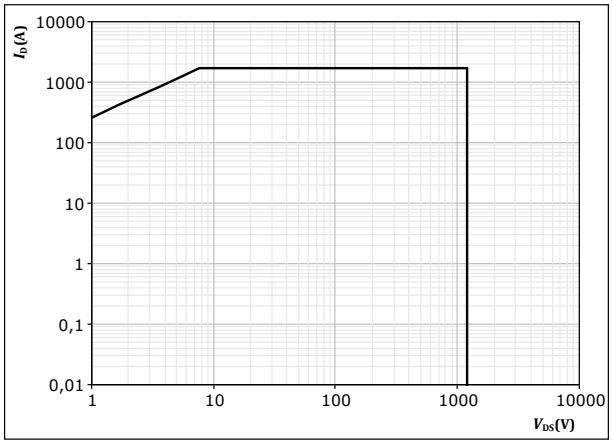
MOSFET thermal model values

R (K/W)	τ (s)
4,75E-02	6,67E+00
5,01E-02	1,05E+00
9,16E-02	1,01E-01
4,48E-02	2,49E-02
1,22E-02	2,57E-03

figure 6. **MOSFET**

Safe operating area

$I_D = f(V_{DS})$



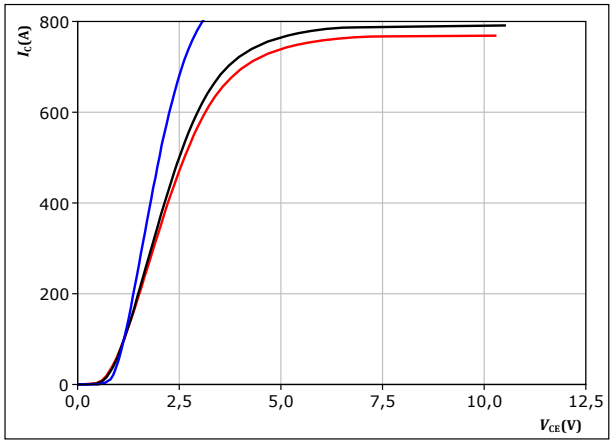
D =	single pulse	
T_s =	80	°C
V_{GS} =	18	V
T_j =	T_{jmax}	

Neutral Point Switch Characteristics

figure 7. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

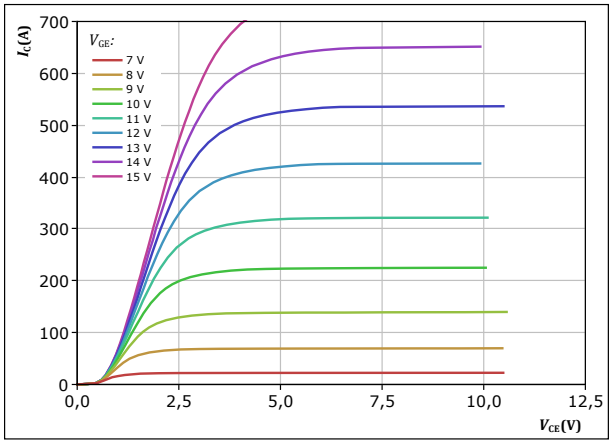


t_p =	250	µs		
V_{GE} =	15	V	T_j:	25 °C
				125 °C
				150 °C

figure 8. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



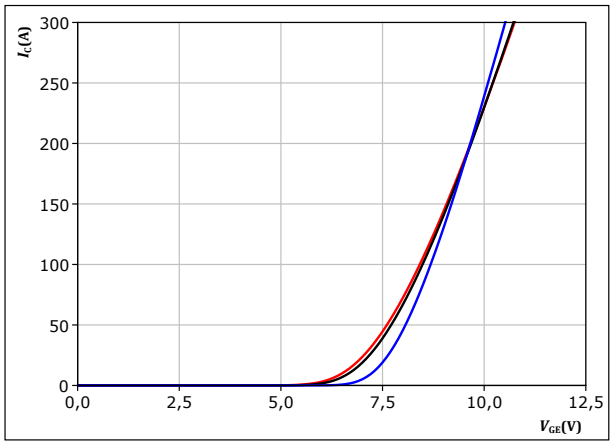
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 15 V in steps of 1 V

figure 9. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

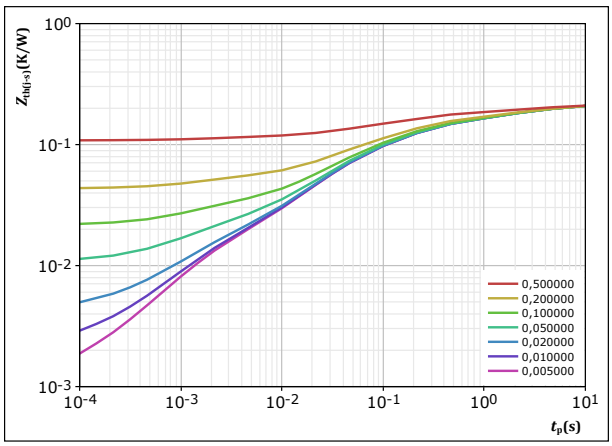


t_p =	250	µs		
V_{CE} =	30	V	T_j:	25 °C
				125 °C
				150 °C

figure 10. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,21	K/W

IGBT thermal model values

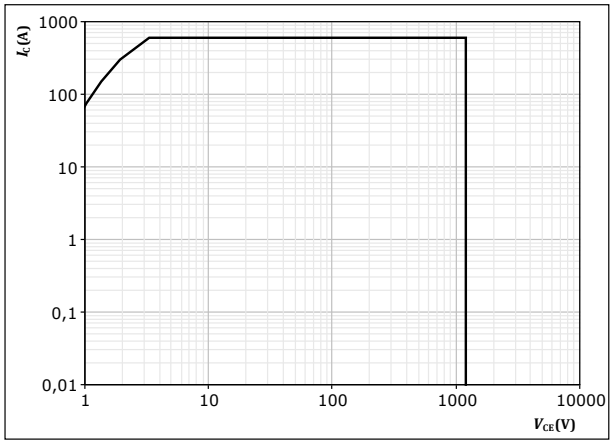
R (K/W)	τ (s)
3,69E-02	6,50E+00
4,35E-02	1,26E+00
7,76E-02	1,57E-01
4,77E-02	2,97E-02
1,07E-02	1,42E-03

Neutral Point Switch Characteristics

figure 11. **IGBT**

Safe operating area

$I_C = f(V_{CE})$

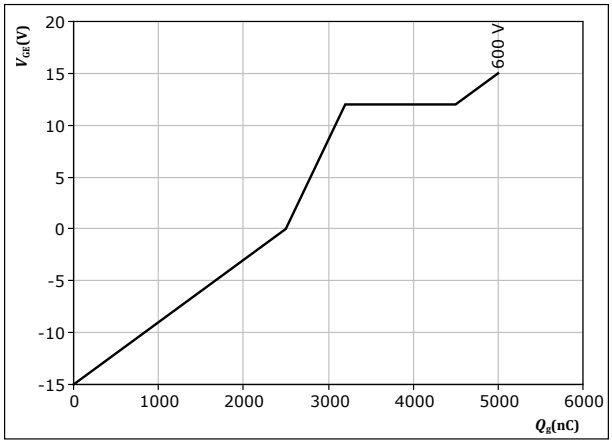


D = single pulse
T_s = 80 °C
V_{GE} = 15 V
T_j = T_{jmax}

figure 12. **IGBT**

Gate voltage vs gate charge

$V_{GE} = f(Q_g)$



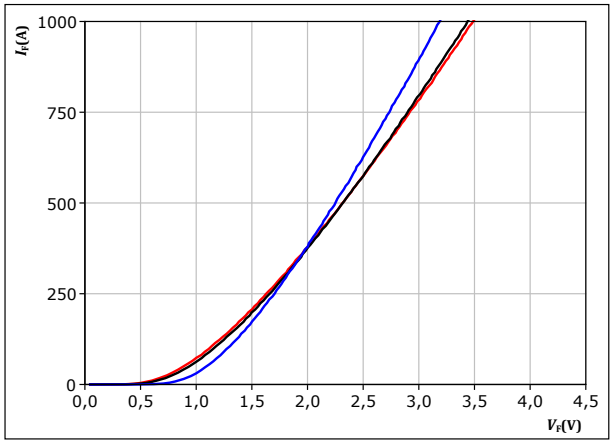
I_C = 300 A
T_j = 25 °C

DC-Link Diode Characteristics

figure 13. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



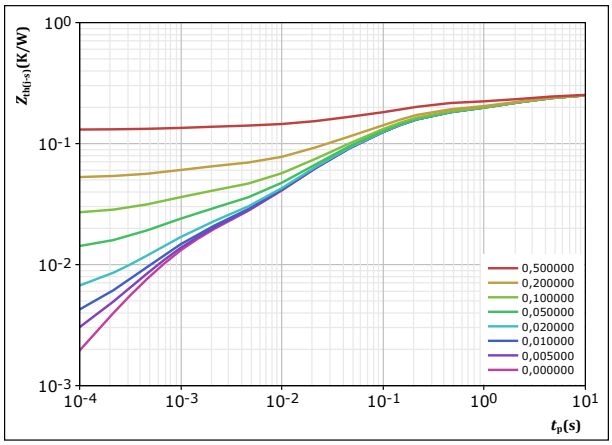
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 14. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,253 K/W

FWD thermal model values

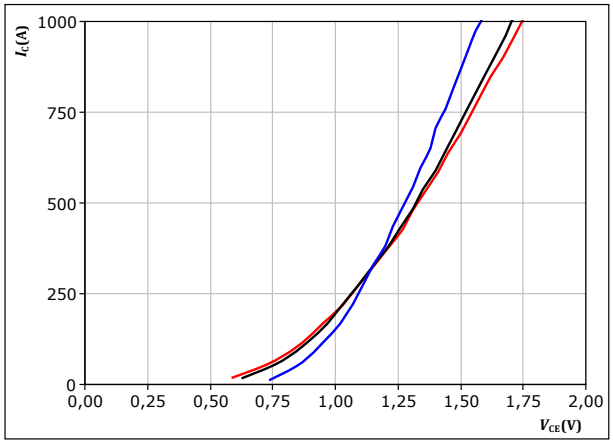
R (K/W)	τ (s)
3,53E-02	7,73E+00
5,84E-02	1,56E+00
1,11E-01	1,14E-01
4,15E-02	1,86E-02
1,41E-02	8,13E-04

DC-Link Switch Characteristics

figure 15. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

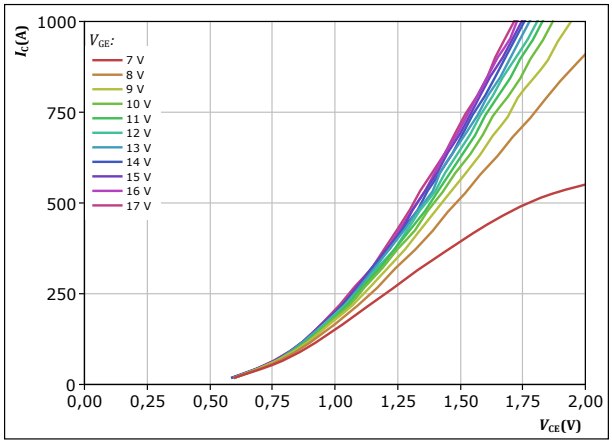


t_p =	250	µs		
V_{GE} =	15	V	T_j:	25 °C
				125 °C
				150 °C

figure 16. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



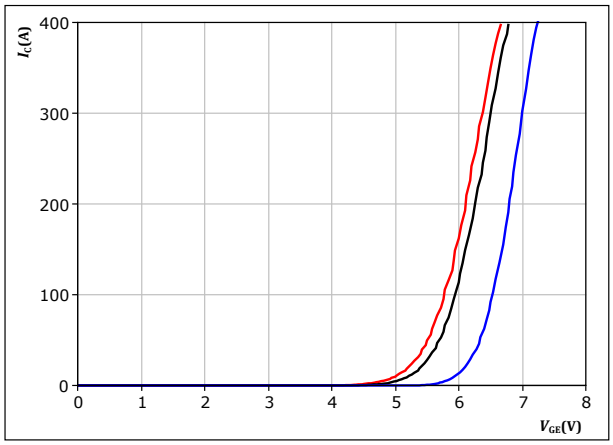
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 17. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

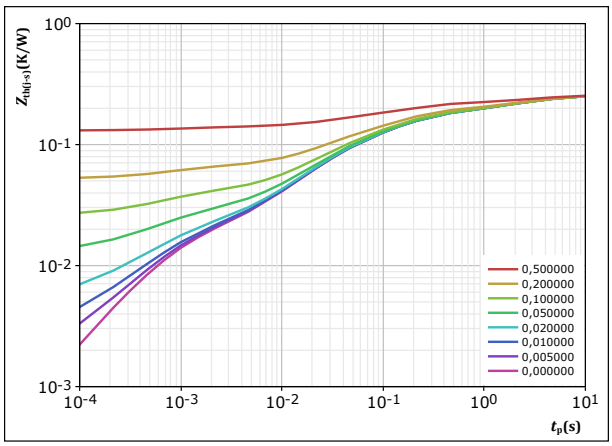


t_p =	250	µs		
V_{CE} =	10	V	T_j:	25 °C
				125 °C
				150 °C

figure 18. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,253	K/W

IGBT thermal model values

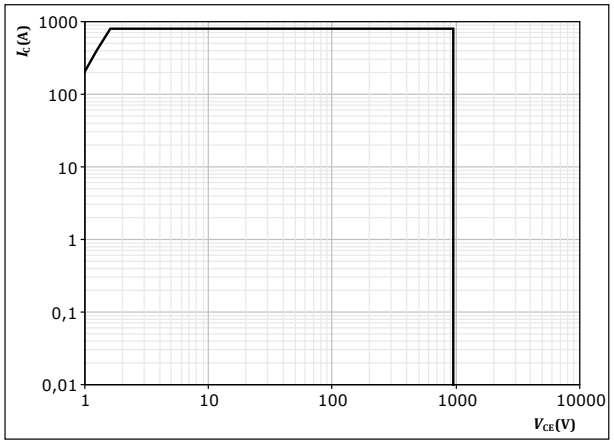
R (K/W)	τ (s)
3,53E-02	7,73E+00
5,58E-02	1,63E+00
9,70E-02	1,38E-01
5,85E-02	2,48E-02
1,45E-02	7,05E-04

DC-Link Switch Characteristics

figure 19. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



D = single pulse

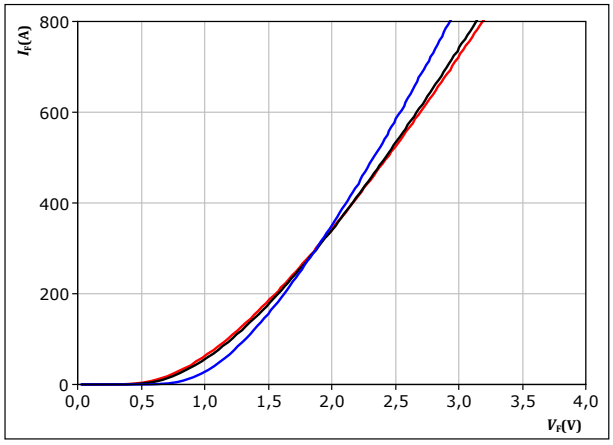
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Neutral Point Diode Characteristics

figure 20. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



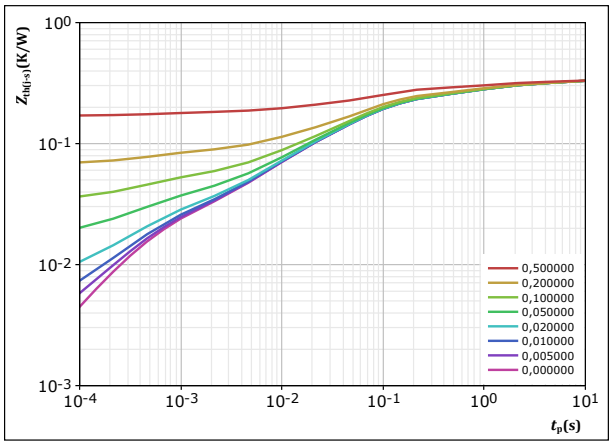
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 21. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,332 K/W

FWD thermal model values

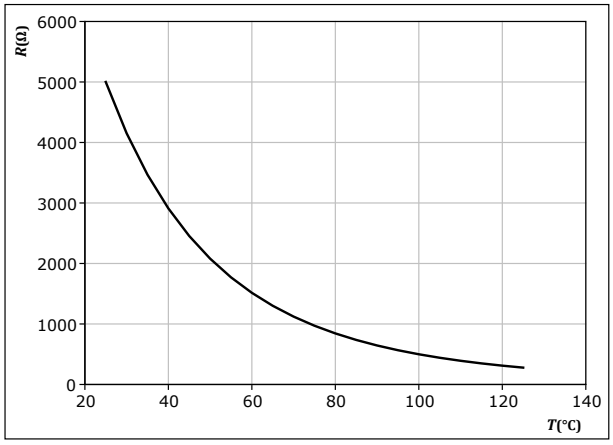
R (K/W)	τ (s)
4,39E-02	6,10E+00
7,51E-02	7,61E-01
1,59E-01	6,84E-02
4,21E-02	8,78E-03
1,93E-02	4,61E-04

Thermistor Characteristics

figure 22. **Thermistor**

Typical NTC characteristic as function of temperature

$R_T = f(T)$

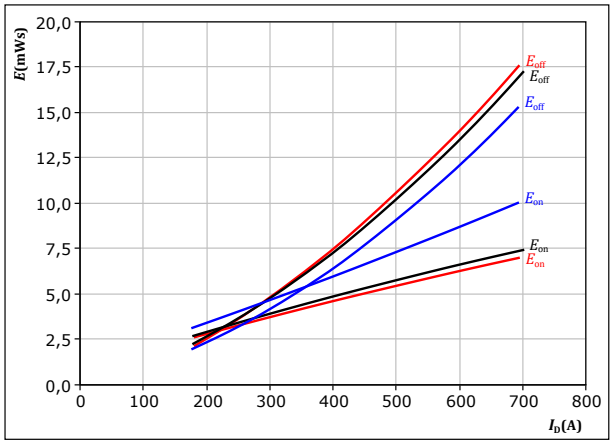


AC Switching Characteristics

figure 23. **MOSFET**

Typical switching energy losses as a function of drain current

$E = f(I_D)$



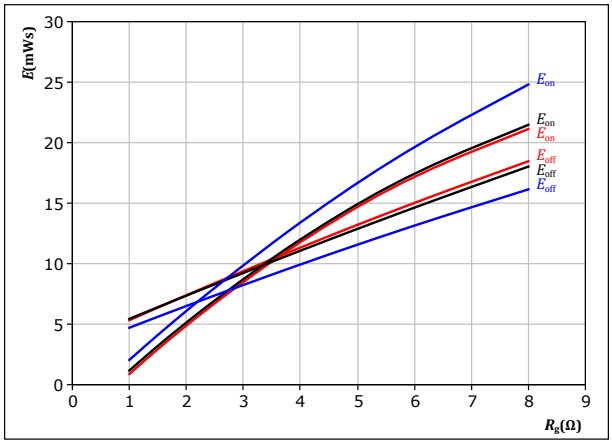
With an inductive load at

V_{DS} =	600	V	T_j:	25 °C
V_{GS} =	-5/18	V		125 °C
R_{gon} =	2	Ω		150 °C
R_{goff} =	2	Ω		

figure 24. **MOSFET**

Typical switching energy losses as a function of MOSFET turn on gate resistor

$E = f(R_g)$



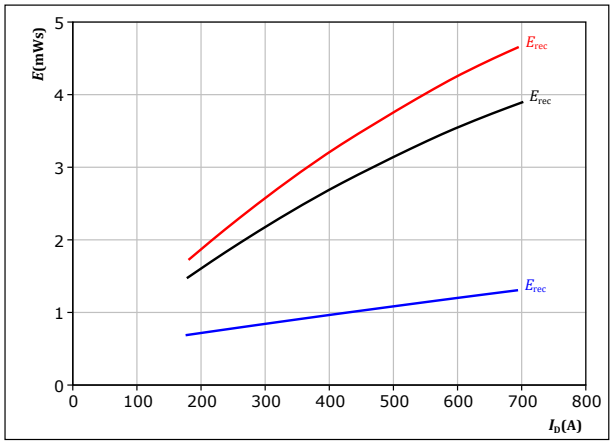
With an inductive load at

V_{DS} =	600	V	T_j:	25 °C
V_{GS} =	-5/18	V		125 °C
I_D =	400	A		150 °C

figure 25. **MOSFET**

Typical reverse recovered energy loss as a function of drain current

$E_{rec} = f(I_D)$



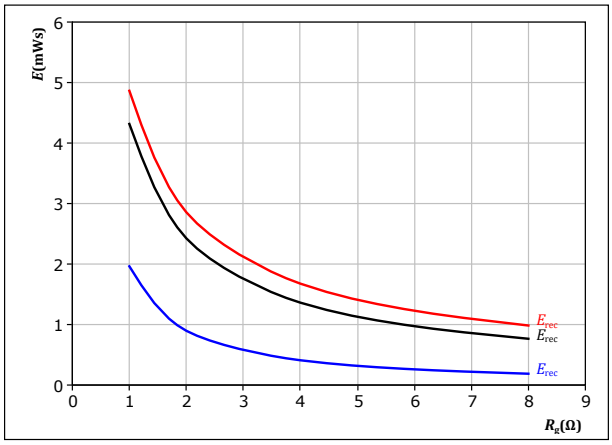
With an inductive load at

V_{DS} =	600	V	T_j:	25 °C
V_{GS} =	-5/18	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 26. **MOSFET**

Typical reverse recovered energy loss as a function of MOSFET turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

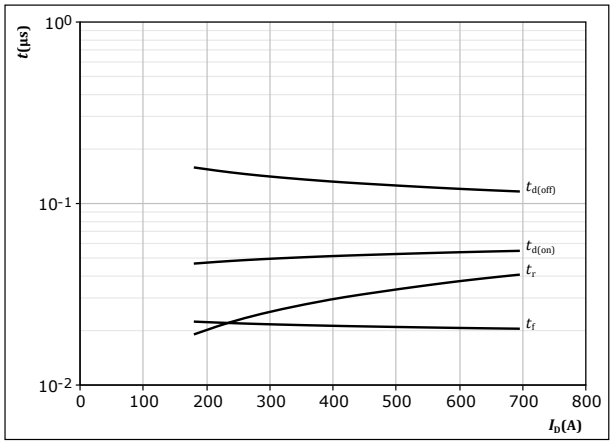
V_{DS} =	600	V	T_j:	25 °C
V_{GS} =	-5/18	V		125 °C
I_D =	400	A		150 °C

AC Switching Characteristics

figure 27. **MOSFET**

Typical switching times as a function of drain current

$t = f(I_D)$



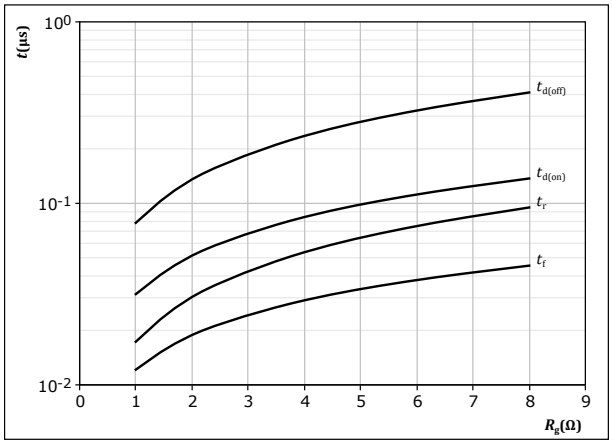
With an inductive load at

T_j =	150	°C
V_{DS} =	600	V
V_{GS} =	-5/18	V
R_{gon} =	2	Ω
R_{goff} =	2	Ω

figure 28. **MOSFET**

Typical switching times as a function of MOSFET turn on gate resistor

$t = f(R_g)$



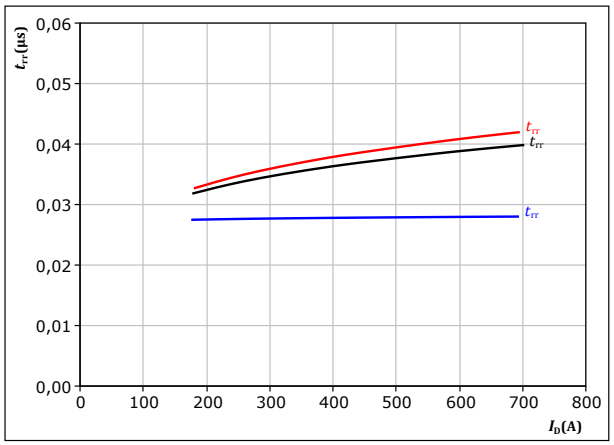
With an inductive load at

T_j =	150	°C
V_{DS} =	600	V
V_{GS} =	-5/18	V
I_D =	400	A

figure 29. **MOSFET**

Typical reverse recovery time as a function of drain current

$t_{rr} = f(I_D)$



At

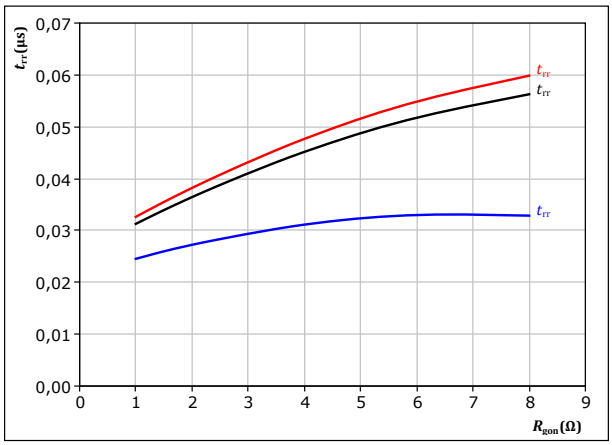
V_{DS} =	600	V
V_{GS} =	-5/18	V
R_{gon} =	2	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 30. **MOSFET**

Typical reverse recovery time as a function of MOSFET turn on gate resistor

$t_{rr} = f(R_{gon})$



At

V_{DS} =	600	V
V_{GS} =	-5/18	V
I_D =	400	A

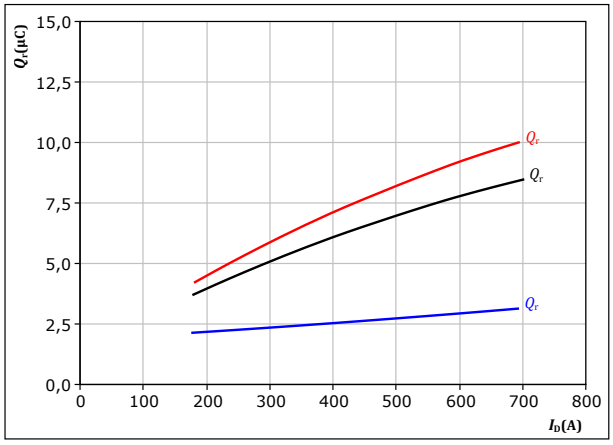
T_j: 25 °C, 125 °C, 150 °C

AC Switching Characteristics

figure 31. **MOSFET**

Typical recovered charge as a function of drain current

$Q_r = f(I_D)$

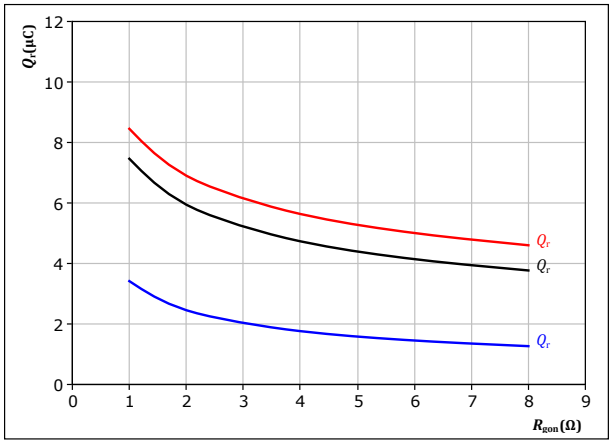


At				T_j:	
	V_{DS} =	600	V		25 °C
	V_{GS} =	-5/18	V		125 °C
	R_{gon} =	2	Ω		150 °C

figure 32. **MOSFET**

Typical recovered charge as a function of MOSFET turn on gate resistor

$Q_r = f(R_{gon})$

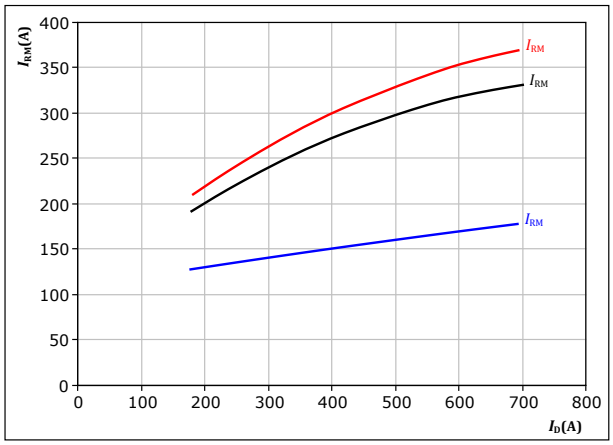


At				T_j:	
	V_{DS} =	600	V		25 °C
	V_{GS} =	-5/18	V		125 °C
	I_D =	400	A		150 °C

figure 33. **MOSFET**

Typical peak reverse recovery current as a function of drain current

$I_{RM} = f(I_D)$

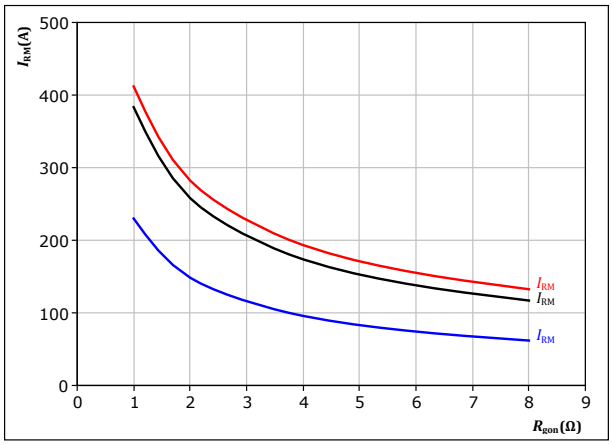


At				T_j:	
	V_{DS} =	600	V		25 °C
	V_{GS} =	-5/18	V		125 °C
	R_{gon} =	2	Ω		150 °C

figure 34. **MOSFET**

Typical peak reverse recovery current as a function of MOSFET turn on gate resistor

$I_{RM} = f(R_{gon})$



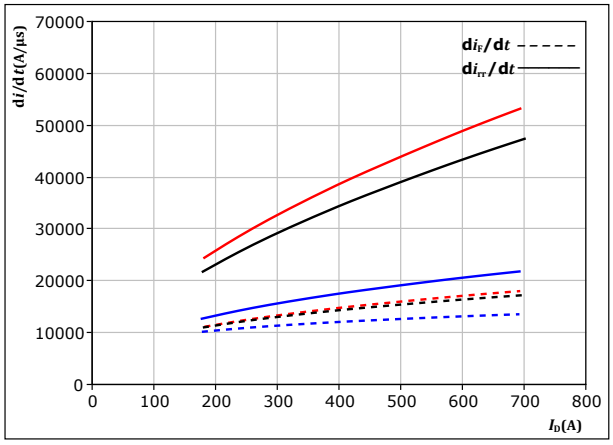
At				T_j:	
	V_{DS} =	600	V		25 °C
	V_{GS} =	-5/18	V		125 °C
	I_D =	400	A		150 °C

AC Switching Characteristics

figure 35. **MOSFET**

Typical rate of fall of forward and reverse recovery current as a function of drain current

di_F/dt, di_{rr}/dt = f(I_D)

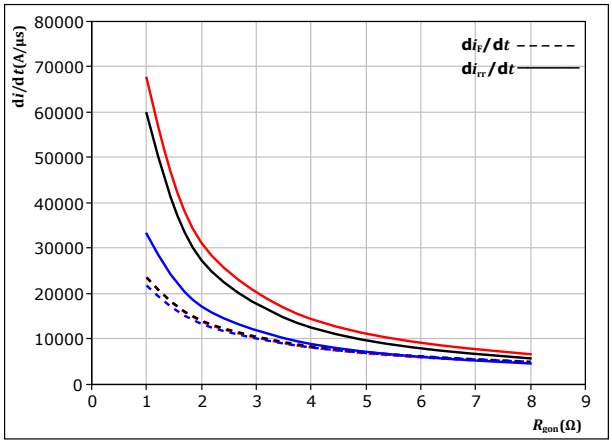


At				
	V_{DS} =	600	V	
	V_{GS} =	-5/18	V	
	R_{gon} =	2	Ω	
	T_j:			25 °C
				125 °C
				150 °C

figure 36. **MOSFET**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})

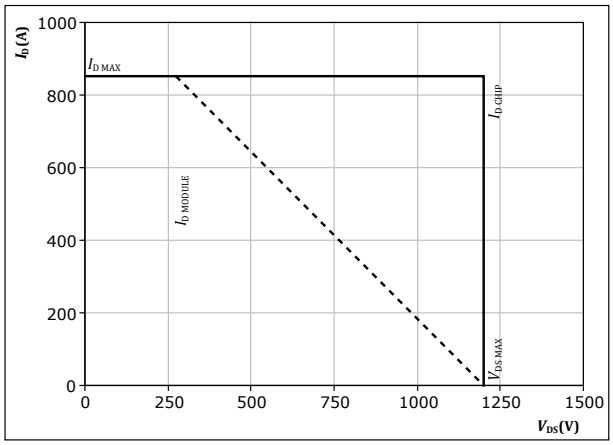


At				
	V_{DS} =	600	V	
	V_{GS} =	-5/18	V	
	I_D =	400	A	
	T_j:			25 °C
				125 °C
				150 °C

figure 37. **MOSFET**

Reverse bias safe operating area

I_D = f(V_{DS})



At			
	T_j =	150	°C
	R_{gon} =	2	Ω
	R_{goff} =	2	Ω

AC Switching Definitions

figure 38. MOSFET

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})

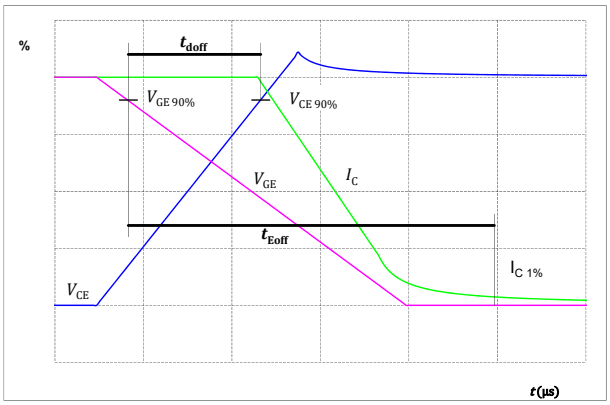


figure 39. MOSFET

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

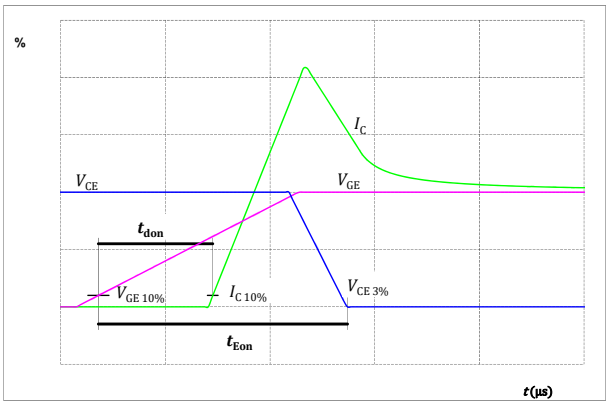


figure 40. MOSFET

Turn-off Switching Waveforms & definition of t_f

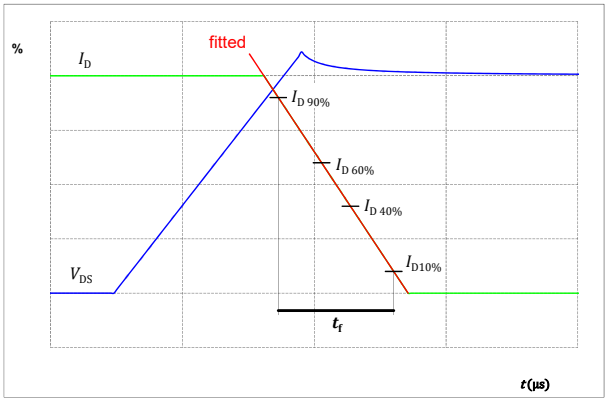
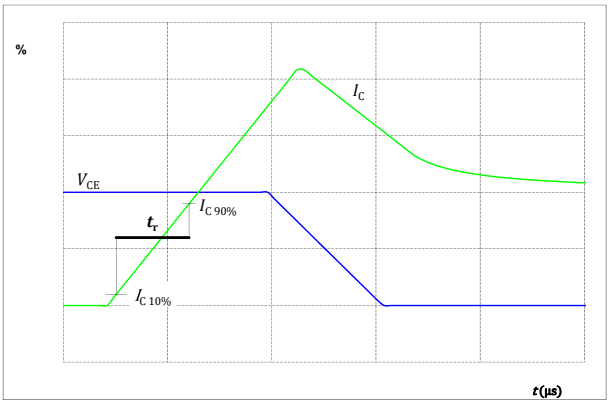


figure 41. MOSFET

Turn-on Switching Waveforms & definition of t_r



AC Switching Definitions

figure 42. **FWD**

Turn-off Switching Waveforms & definition of t_{trr}

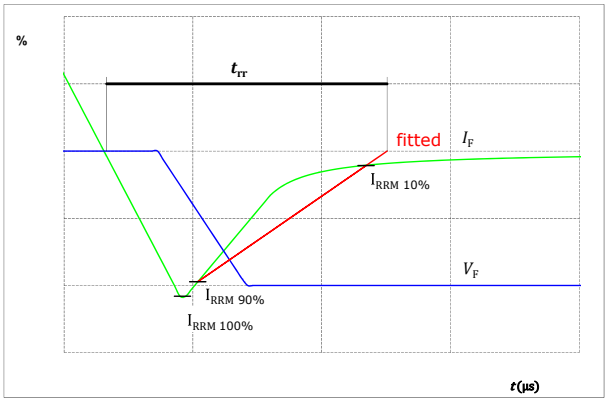


figure 43. **FWD**

Turn-on Switching Waveforms & definition of t_{Qrr} (t_{Qrr} = integrating time for Q_{rr})

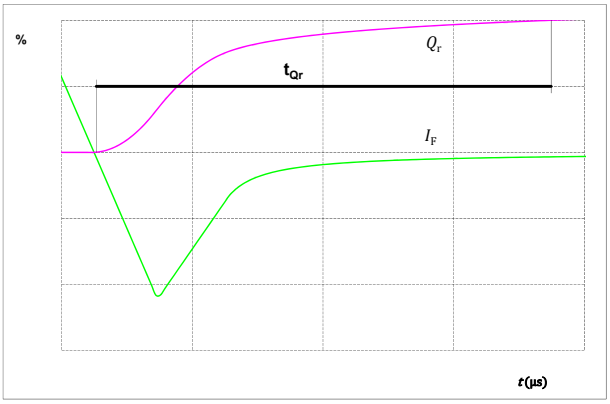
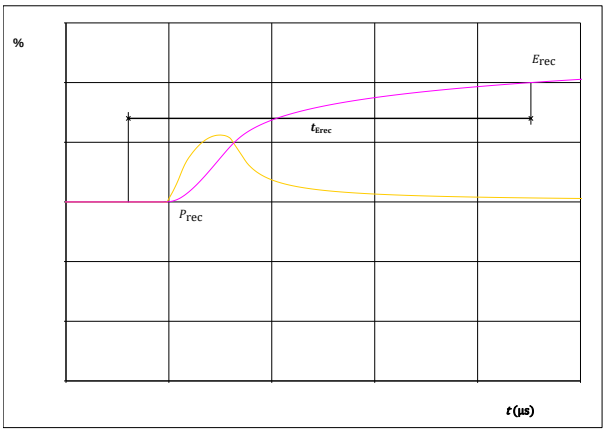


figure 44. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



Ordering Code

Version	Ordering Code
Without thermal paste	30-E312NAA003MS13-PS48F75Z
With thermal paste (5,2 W/mK, PTM6000HV)	30-E312NAA003MS13-PS48F75Z-/7/

Marking

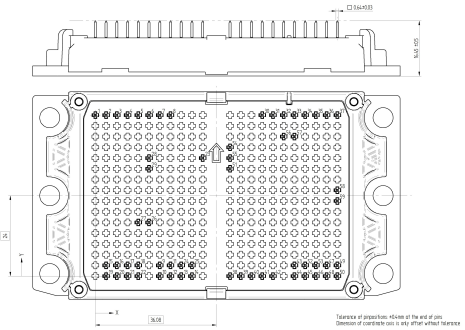
	Name	Date code	Logo	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV	WWYY	VIN	LLLLL	SSSS

Datamatrix	Type&Ver	Lot number	Serial	Date code		
	TTTTTTVV	LLLLL	SSSS	WWYY		

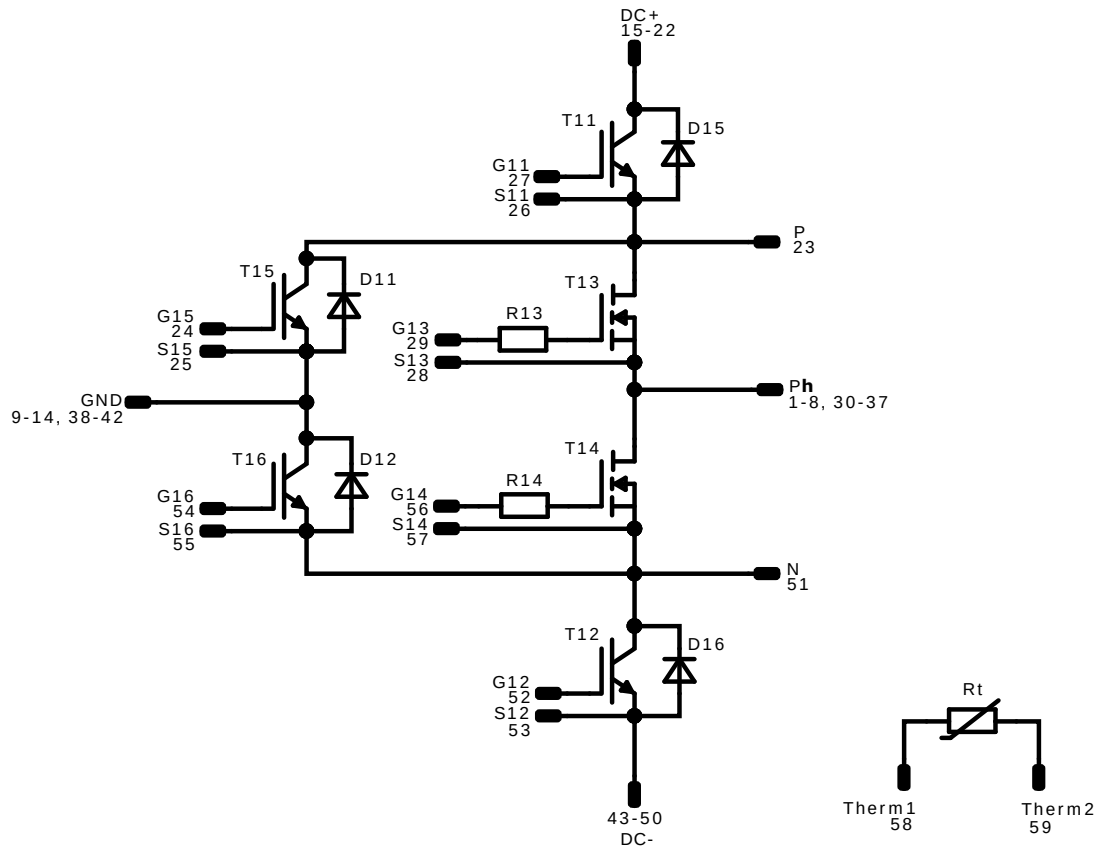
Outline

Pin table [mm]

Pin	X	Y	Function	31	52,96	48	Ph
1	0	48	Ph	32	56,16	48	Ph
2	3,2	48	Ph	33	59,36	48	Ph
3	6,4	48	Ph	34	62,56	48	Ph
4	9,6	48	Ph	35	65,76	48	Ph
5	12,8	48	Ph	36	68,96	48	Ph
6	16	48	Ph	37	72,16	48	Ph
7	19,2	48	Ph	38	40,16	0	GND
8	22,4	48	Ph	39	43,36	0	GND
9	19,2	3,2	GND	40	46,56	0	GND
10	19,2	0	GND	41	49,76	0	GND
11	22,4	3,2	GND	42	52,96	0	GND
12	22,4	0	GND	43	59,36	3,2	DC-
13	25,6	0	GND	44	59,36	0	DC-
14	28,8	0	GND	45	62,56	0	DC-
15	3,2	3,2	DC+	46	65,76	0	DC-
16	6,4	3,2	DC+	47	68,96	3,2	DC-
17	9,6	3,2	DC+	48	68,96	0	DC-
18	12,8	3,2	DC+	49	72,16	3,2	DC-
19	3,2	0	DC+	50	72,16	0	DC-
20	6,4	0	DC+	51	40,16	32	N
21	9,6	0	DC+	52	62,56	3,2	G12
22	12,8	0	DC+	53	65,76	3,2	S12
23	32	35,2	P	54	40,16	38,4	G16
24	25,6	3,2	G15	55	40,16	35,2	S16
25	28,8	3,2	S15	56	56,16	41,6	G14
26	16	16	S11	57	59,36	41,6	S14
27	12,8	16	G11	58	72,16	25,6	Therm1
28	16	35,2	S13	59	72,16	22,4	Therm2
29	16	32	G13				
30	49,76	48	Ph				



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T13, T14	MOSFET	1200 V	2,83 mΩ	AC Switch	
T15, T16	IGBT	1200 V	300 A	Neutral Point Switch	
D15, D16	FWD	1200 V	400 A	DC-Link Diode	
T11, T12	IGBT	950 V	400 A	DC-Link Switch	
D11, D12	FWD	1200 V	300 A	Neutral Point Diode	
R13, R14	Resistor			Resistor (Gate)	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 24	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E3BP packages see vincotech.com website.

Package data
Package data for *flow* E3BP packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
Certification pending. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
30-E312NAA003MS13-PS48F75Z-D1-14	27 Mar. 2026	Initial Release	